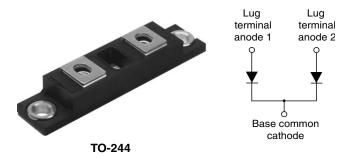


Vishay High Power Products

HEXFRED® Ultrafast Soft Recovery Diode, 210 A



PRODUCT SUMMARY				
I _{F(AV)}	210 A			
V_{R}	600 V			
I _{F(DC)} at T _C	120 A at 100 °C			

FEATURES

- Very low Q_{rr} and t_{rr}
- Lead (Pb)-free
- · Designed and qualified for industrial level



ROHS

BENEFITS

- · Reduced RFI and EMI
- · Reduced snubbing

DESCRIPTION

HEXFRED[®] diodes are optimized to reduce losses and EMI/RFI in high frequency power conditioning systems. An extensive characterization of the recovery behavior for different values of current, temperature and dl/dt simplifies the calculations of losses in the operating conditions. The softness of the recovery eliminates the need for a snubber in most applications. These devices are ideally suited for power converters, motors drives and other applications where switching losses are significant portion of the total losses.

ABSOLUTE MAXIMUM RATINGS					
PARAMETER	SYMBOL	TEST CONDITIONS	MAX.	UNITS	
Cathode to anode voltage	V _R		600	V	
Continuous forward current		T _C = 25 °C	235		
Continuous forward current	I _F	T _C = 100 °C	120	Α	
Single pulse forward current	I _{FSM}	Limited by junction temperature	600		
Non-repetitive avalanche energy	E _{AS}	L = 100 μH, duty cycle limited by maximum T _J	2.2	mJ	
Manianum nauran disainatian	T _C = 25 °C	463	W		
Maximum power dissipation P _D		T _C = 100 °C	185		
Operating junction and storage temperature range	T _J , T _{Stg}		- 55 to + 150	°C	

ELECTRICAL SPECIFICATIONS PER LEG (T _J = 25 °C unless otherwise specified)							
PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNITS
Cathode to anode breakdown voltage	V _{BR}	Ι _R = 100 μΑ		600	-	-	
Maximum forward voltage V _{FM}		I _F = 105 A		-	1.38	1.9	V
	I _F = 210 A	See fig. 1	-	1.6	2.25		
		I _F = 105 A, T _J = 125 °C	-	1.3	1.56		
Maximum reverse leakage current	I _{RM}	T _J = 125 °C, V _R = 480 V	See fig. 2	-	1.8	6.0	mA
Junction capacitance	C _T	V _R = 200 V	See fig. 3	-	200	300	pF
Series inductance	L _S	From top of terminal hole to mounting plane - 6.0 -		-	nH		

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DYNAMIC RECOVERY CHARACTERISTICS (T _J = 25 °C unless otherwise specified)							
PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNITS
			$I_F = 1.0 \text{ A}, dI_F/dt = 200 \text{ A/}\mu\text{s}, V_R = 30 \text{ V}$		35	-	
Reverse recovery time See fig. 5	t _{rr}	T _J = 25 °C		-	90	140	ns
occ lig. o		T _J = 125 °C		-	160	240	
Peak recovery current	I _{RRM}	T _J = 25 °C		-	10	18	۸
See fig. 6		IRRM	T _J = 125 °C	I _F = 105 A dI _F /dt = 200 A/μs	-	15	30
Reverse recovery charge	Q _{rr}	T _J = 25 °C	$V_{\rm B} = 200 \text{ V}$	-	450	1300	nC
See fig. 7		T _J = 125 °C		-	1200	3600	IIC
Peak rate of recovery current	dl/200/M/dt	T _J = 25 °C		-	310	-	Λ/μο
See fig. 8		T _J = 125 °C		-	240	-	A/μs

THERMAL - MECHANICAL SPECIFICATIONS						
PARAMETER		SYMBOL	MIN.	TYP.	MAX.	UNITS
Maximum junction and storage temperature range		T _J , T _{Stg}	- 55	-	150	°C
Thermal registence, junction to acco	per leg	R_{thJC}	-	-	0.27	°C/W K/W
Thermal resistance, junction to case	per module		-	-	0.135	
Typical thermal resistance, case to heatsink		R _{thCS}	R _{thCS} - 0.10 -		1,111	
Weight			-	68	-	g
			-	2.4	-	oz.
Mounting torque (1)			30 (3.4)	-	40 (4.6)	
Mounting torque center hole Terminal torque			12 (1.4)	-	18 (2.1)	N ⋅ m (lbf ⋅ in)
			30 (3.4)	-	40 (4.6)	(.2)
Vertical pull			-	-	80	lbf ⋅ in
2" lever pull			-	-	35	IOI · III

Note

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⁽¹⁾ Mounting surface must be smooth, flat, free of burrs or other protrusions. Apply a thin even film or thermal grease to mounting surface. Gradually tighten each mounting bolt in 5 to 10 lbf \cdot in steps until desired or maximum torque limits are reached





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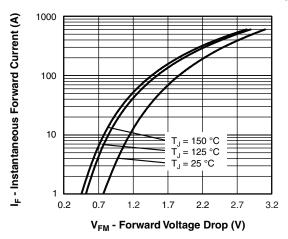


Fig. 1 - Maximum Forward Voltage Drop vs. Instantaneous Forward Current (Per Leg)

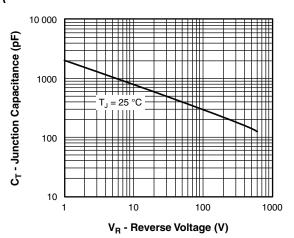


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage (Per Leg)

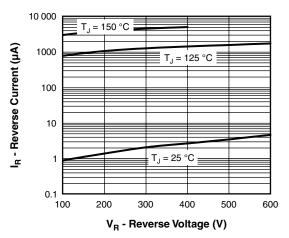


Fig. 2 - Typical Reverse Current vs. Reverse Voltage (Per Leg)

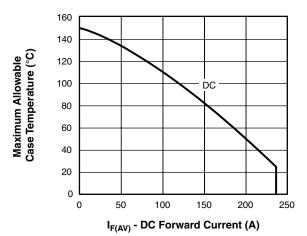


Fig. 4 - Maximum Allowable Case Temperature vs. DC Forward Current (Per Leg)

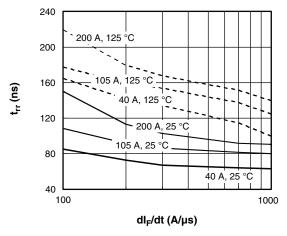


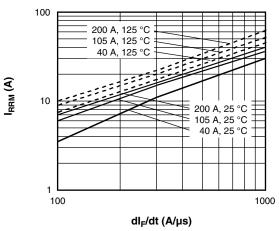
Fig. 5 - Typical Reverse Recovery Time vs. dl_F/dt (Per Leg)

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4000





3500 200 A, 125 3000 2500 105 A, 125 2000 40 A, 125 1500 200 A, 25 1000 105 A, 25 °C 500 0 100 1000 dl_F/dt (A/μs)

Fig. 6 - Typical Recovery Current vs. dI_F/dt (Per Leg)

Fig. 7 - Typical Stored Charge vs. dI_F/dt (Per Leg)

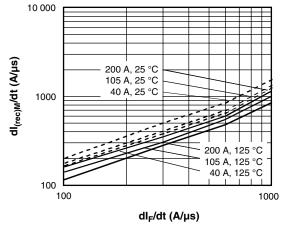


Fig. 8 - Typical $dI_{(rec)M}/dt$ vs. dI_F/dt (Per Leg)

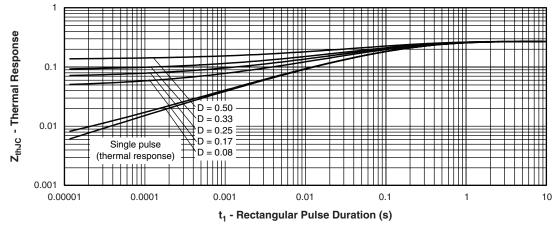


Fig. 9 - Maximum Thermal Impedance Z_{thJC} Characteristics (Per Leg)



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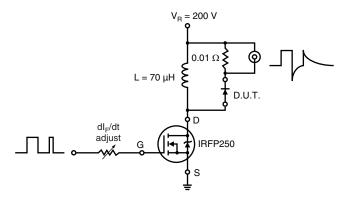
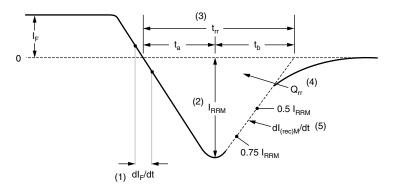


Fig. 10 - Reverse Recovery Parameter Test Circuit



- (1) dl_F/dt rate of change of current through zero crossing
- (2) I_{RRM} peak reverse recovery current
- (3) $t_{\rm rr}$ reverse recovery time measured from zero crossing point of negative going $I_{\rm F}$ to point where a line passing through 0.75 $I_{\rm RRM}$ and 0.50 $I_{\rm RRM}$ extrapolated to zero current.
- (4) $\mathbf{Q}_{\rm rr}$ area under curve defined by $\mathbf{t}_{\rm rr}$ and $\mathbf{I}_{\rm RRM}$

$$Q_{rr} = \frac{t_{rr} \times I_{RRM}}{2}$$

(5) dI_{(rec)M}/dt - peak rate of change of current during t_b portion of t_{rr}

Fig. 11 - Reverse Recovery Waveform and Definitions

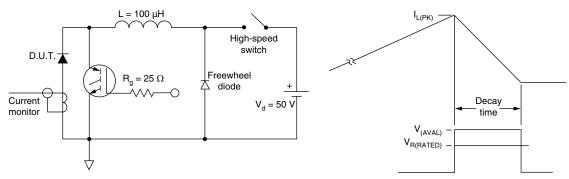


Fig. 12 - Avalanche Test Circuit and Waveforms

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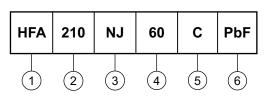
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ORDERING INFORMATION TABLE

Device code



1 - HEXFRED® family, electron irradiated

2 - Average current rating

3 - NJ = TO-244

4 - Voltage rating (60 = 600 V)

5 - C = Common cathode

6 - Lead (Pb)-free

LINKS TO RELATED DOCUMENTS					
Dimensions http://www.vishay.com/doc?95021					

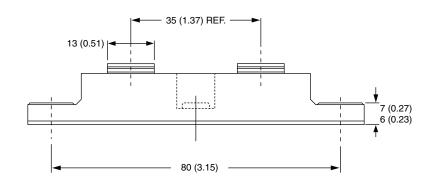
Document Number: 94062 Revision: 01-Aug-08

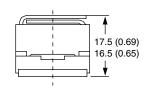


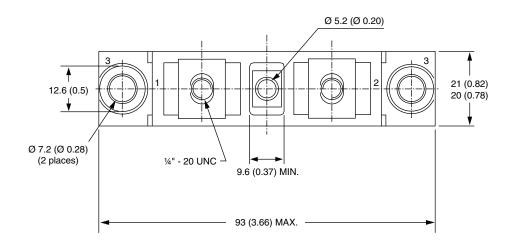
Vishay Semiconductors

TO-244

DIMENSIONS in millimeters (inches)









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